Docket No.: H0498.70130US01

(PATENT)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Serial No: Tao Deng et al. 10/763.819

Confirmation No.:

5026

Filed:

January 23, 2004

For:

FABRICATION OF METALLIC MICROSTRUCTURES VIA

EXPOSURE OF PHOTOSENSITIVE COMPOSITION

Examiner: K. Duda

Art Unit:

1795

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted via the Office electronic filling system in accordance with \$ 1.5(a)(4)

Dated: (014108

TRANSMITTAL LETTER

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Enclosed are the following items for filing in connection with the above-referenced Patent Application:

- 1. Power of Attorney and
- 2. Statement under 37 C.F.R. 3.73(b).

The Director is hereby authorized to charge any deficiency or credit any overpayment in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper

hereafter filed in this application by this firm) to our Deposit Account No. 23/2825, under Docket No. H0498.70130US01.

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Dated: 06/04/02

Respectfully submitted,

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